# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4175318

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| **SUBMISSION TYPE:** | NEW ASSIGNMENT |
| **NATURE OF CONVEYANCE:** | ASSIGNMENT |

**CONVEYING PARTY DATA**

| Name | Execution Date |
|---|---|
| MINGZHU WANG | 11/16/2016 |
| BOJIE ZHAO | 11/21/2016 |
| TAKEHIKO TANAKA | 11/15/2016 |
| NAN GUO | 11/16/2016 |
| ZHENYU CHEN | 11/16/2016 |
| HENG JIANG | 11/16/2016 |
| ZHONGYU LUAN | 11/17/2016 |
| FENGSHENG XI | 11/17/2016 |
| FEIFAN CHEN | 11/16/2016 |
| LIANG DING | 11/16/2016 |

**RECEIVING PARTY DATA**

| | |
|---|---|
| **Name:** | NINGBO SUNNY OPOTECH CO., LTD. |
| **Street Address:** | 66-68, SHUNYU ROAD, YUYAO, |
| **City:** | NINGBO, ZHEJIANG |
| **State/Country:** | CHINA |
| **Postal Code:** | 315400 |

**PROPERTY NUMBERS Total: 1**

| Property Type | Number |
|---|---|
| **Application Number:** | 15317117 |

**CORRESPONDENCE DATA**

**Fax Number:** (626)571-9813

***Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.***

**Phone:** 626-571-9812
**Email:** RAYMONDC@DAVIDANDRAYMOND.COM
**Correspondent Name:** DAVID AND RAYMOND PATENT FIRM
**Address Line 1:** 108 N. YNEZ AVE., SUITE 128
**Address Line 4:** MONTEREY PARK, CALIFORNIA 91754

| | |
|---|---|
| **ATTORNEY DOCKET NUMBER:** | USP5996C/NB2397-SYO |

| | |
|---|---|
| **NAME OF SUBMITTER:** | MICHAEL LEE |
| **SIGNATURE:** | /Michael Lee/ |
| **DATE SIGNED:** | 12/08/2016 |

**Total Attachments: 10**
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**UTILITY PATENT**

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Mingzhu Wang
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly and Manufacturing Method Thereof for Electronic Device
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

☒ executed on even data herewith
☐ executed on:
☐ filed on: Serial No.:

WHEREAS, Ningbo Sunny Opotech Co.,Ltd.
whose post office address is 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Mingzhu Wang
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

Mingzhu Wang
SIGNATURE

2016.11.16.
DATE

**UTILITY PATENT**

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Bojie Zhao
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly and Manufacturing Method Thereof for Electronic Device
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

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hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Bojie Zhao
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

Bojie Zhao
SIGNATURE

2016.11.21
DATE

UTILITY PATENT

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Takehiko Tanaka
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly and Manufacturing Method Thereof for Electronic Device
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

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☐ executed on:
☐ filed on: Serial No.:

WHEREAS, Ningbo Sunny Opotech Co.,Ltd.
whose post office address is 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Takehiko Tanaka
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

Takehiko Tanaka
SIGNATURE

2016.11.15
DATE

**UTILITY PATENT**

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Nan Guo
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly and Manufacturing Method Thereof for Electronic Device
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was
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☐ executed on:
☐ filed on: Serial No.:

WHEREAS, Ningbo Sunny Opotech Co.,Ltd.
whose post office address is 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Nan Guo
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

Nan Guo
SIGNATURE

2016. 11. 16
DATE

**UTILITY PATENT**

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Zhenyu Chen
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly and Manufacturing Method Thereof for Electronic Device
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

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☐ filed on: Serial No.:

WHEREAS, Ningbo Sunny Opotech Co.,Ltd.
whose post office address is 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Zhenyu Chen
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

Zhenyu Chen
SIGNATURE

2016.11.16
DATE

**UTILITY PATENT**

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Heng Jiang
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly and Manufacturing Method Thereof for Electronic Device
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hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Heng Jiang
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

Heng Jiang
SIGNATURE

2016.11.16
DATE

**UTILITY PATENT**

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Zhongyu Luan
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly and Manufacturing Method Thereof for Electronic Device
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hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Zhongyu Luan
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

| | |
|---|---|
| Zhongyu Luan | 2016.11.17 |
| SIGNATURE | DATE |

UTILITY PATENT

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Fengsheng Xi
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly and Manufacturing Method Thereof for Electronic Device
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

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ASSIGNOR NAME: Fengsheng Xi
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

Fengsheng Xi
SIGNATURE

2016.11.17
DATE

**UTILITY PATENT**

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Feifan Chen
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly and Manufacturing Method Thereof for Electronic Device
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whose post office address is 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400
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NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Feifan Chen
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

Feifan Chen
SIGNATURE

2016.11.16
DATE

**UTILITY PATENT**

Attorney's
Docket No.: USP5996C-NB2397-SYO

# ASSIGNMENT

WHEREAS, I (we), Liang Ding
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in
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NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Liang Ding
ADDRESS: 66-68 Shunyu Road,Yuyao City,Ningbo,Zhejiang Province,China 315400

SIGNATURE

2016.11.16
DATE